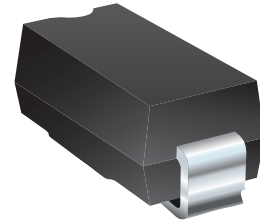


Product Change Notification

CHIP DIODES

Bourns Manufacturers Representatives
Corporate Distributor Product Managers
Americas Sales Team
Asia Sales Team
Europe Sales Team



February, 2011

Bourns® Semiconductor Products Announces the Addition of Back-end Package Assembly Location

Bourns is adding back-end package assembly capacity in Taiwan for the diode part numbers below to help ensure continued secure supply chain management and delivery support to our customers.

Bourns P/N	Bourns P/N
SMAJ Series	CD214A-TxxLF Series
SMBJ Series	CD214B-TxxLF Series
SMCJ Series	CD214C-TxxLF Series
SMLJ Series	CD214L-TxxLF Series

Reliability data, SGS and MDS reports on the package assembly incorporating the above changes have been available since January 1, 2011.

Bourns is issuing 90 days notice that mass production using the above back-end package assembly location will be available beginning March 31, 2011.

Product data sheet specifications will continue to be met with no change to fit, form or function and we do not anticipate any impact to our customers' applications.

Some product will be available immediately if requested by customers.

If you have any questions, please contact [Bourns Customer Service](#).